

P-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- Advanced Trench Technology
- Low gate charge
- Excellent $R_{DS(ON)}$

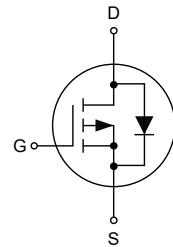
1.2 Applications

- Brushless motor
- Uninterruptible power supply
- Load switch

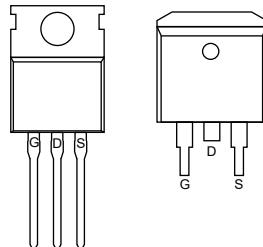
1.3 Quick reference

$V_{DS} = -100V$
 $I_D = -50A$
 $R_{DS(ON)} \leq 52m\Omega @ V_{GS} = 10V$ (Type: 40m Ω)

Symbol



Simplified Outline



2. Package Marking and Ordering Information

Product Name	Package	Marking		Reel Size	Tape width	Quantity
KJ50P10C	TO-220	50P10	YWWXXX:	-	-	1000
KJ50P10D	TO-263	YWWXXX	Date Code	-	-	800

3. Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Min	Max	Unit
V_{DS}	Drain-Source Voltage	-100	-	V
V_{GS}	Gate-Source Voltage	-	± 20	V
I_D ¹	Continuous Drain Current, $V_{GS} @ -10V$	-	-50	A
	Continuous Drain Current, $V_{GS} @ -100V$	-	-28	A
I_{DM} ²	Pulsed Drain Current	-	-150	A
E_{AS} ³	Single Pulsed Avalanche Energy	-	87	mJ
P_{tot} ⁴	Total Power Dissipation	-	140	W
T_{stg}	Storage Temperature	-55	150	°C
T_J	Junction Temperature	-	150	°C
$R_{\theta JA}$ ¹	Thermal Resistance-Junction to ambient	-	62	°C/W
$R_{\theta JC}$ ¹	Thermal Resistance-Junction to Case	-	1.1	°C/W

4. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-100\text{V}$, $V_{\text{GS}}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=\pm20\text{V}$	-	-	±100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=-250\mu\text{A}$	-1	-1.6	-2.5	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source on-Resistance	$V_{\text{GS}}=-10\text{V}$, $I_D=-20\text{A}$	-	40	52	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source on-Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-10\text{A}$	-	44	62	$\text{m}\Omega$
C_{iss}	Input Capacitance	$V_{\text{DS}}=-50\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$	-	2120	-	pF
C_{oss}	Output Capacitance		-	194	-	pF
C_{rss}	Reverse Transfer Capacitance		-	13	-	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-50\text{V}$, $I_D=-5\text{A}$, $V_{\text{GS}}=-10\text{V}$	-	40	-	nC
Q_{gs}	Gate-Source Charge		-	7.8	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	8.6	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-50\text{V}$, $I_D=-5\text{A}$, $R_G=6\Omega$, $V_{\text{GS}}=-10\text{V}$	-	13	-	ns
t_r	Turn-on Rise Time		-	39	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	100.1	-	ns
t_f	Turn-off Fall Time		-	105.3	-	ns
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-35	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-140	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=-30\text{A}$	-	-	-1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_F=-5\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	104	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	280	-	nC

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. The E_{AS} data shows Max. rating. The test condition is $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-24\text{A}$.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

5. Typical Characteristics

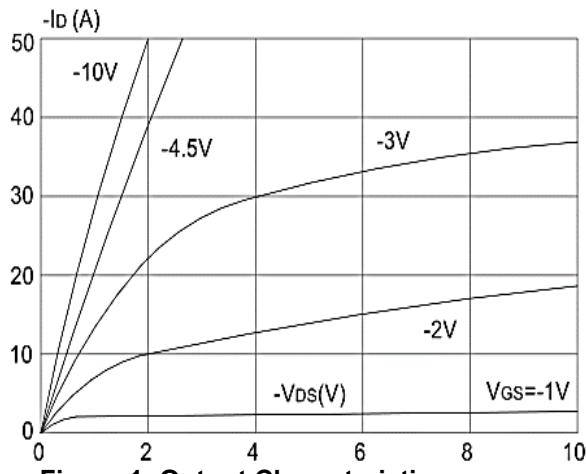


Figure 1: Output Characteristics

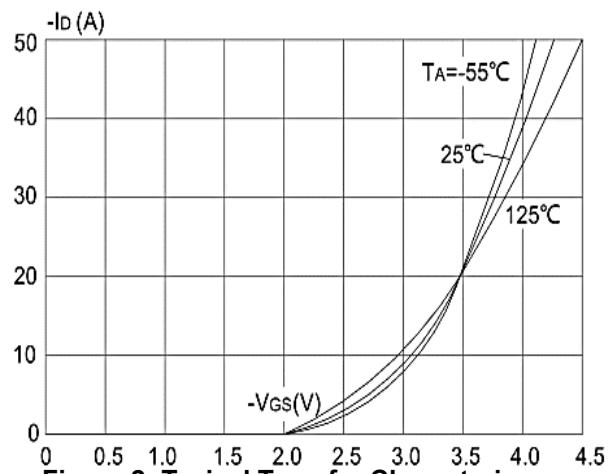


Figure 2: Typical Transfer Characteristics

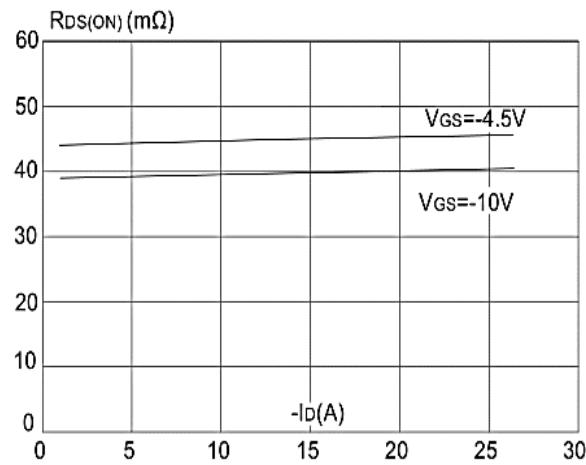


Figure 3: On-resistance vs. Drain Current

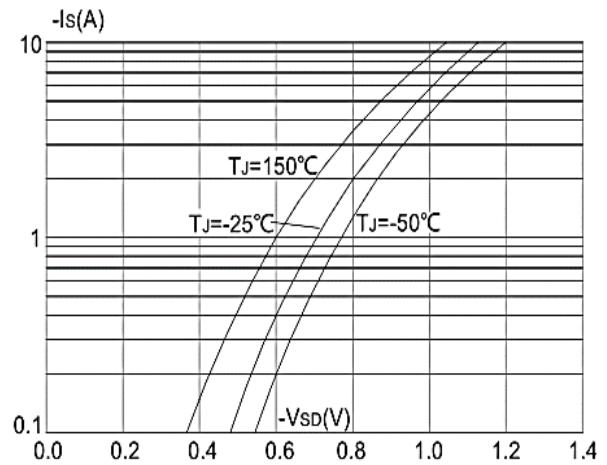


Figure 4: Body Diode Characteristics

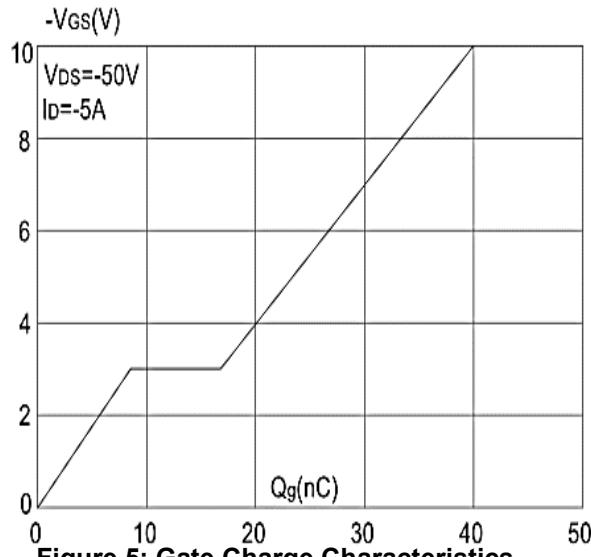


Figure 5: Gate Charge Characteristics

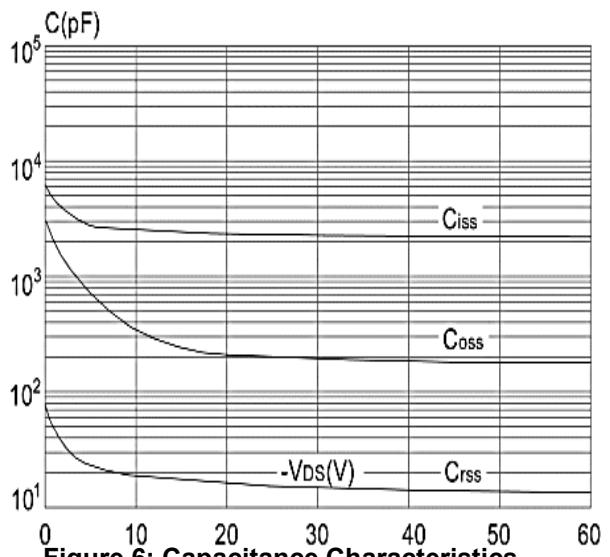


Figure 6: Capacitance Characteristics

5. Typical Characteristics(cont.)

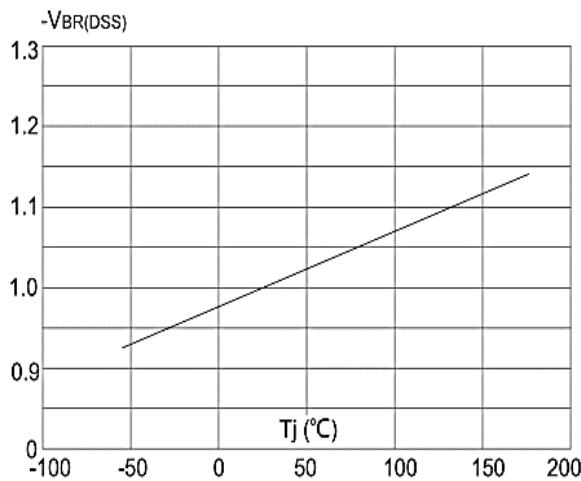


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

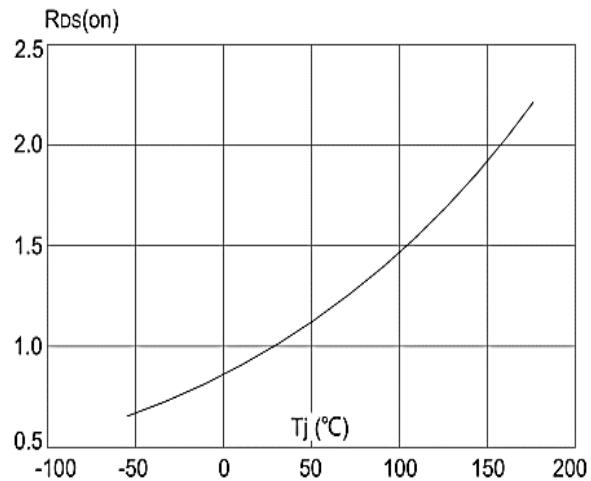


Figure 8: Normalized on Resistance vs. Junction Temperature

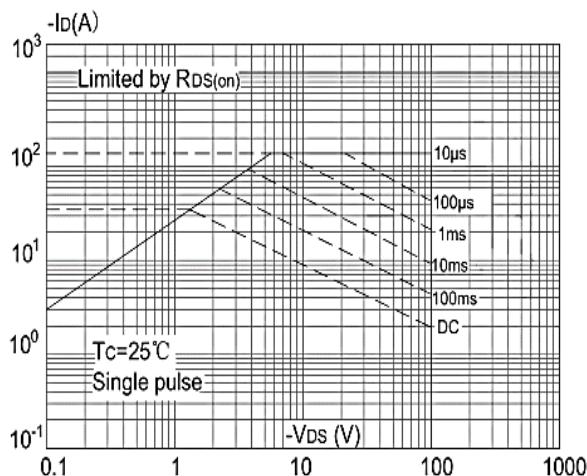


Figure 9: Maximum Safe Operating Area

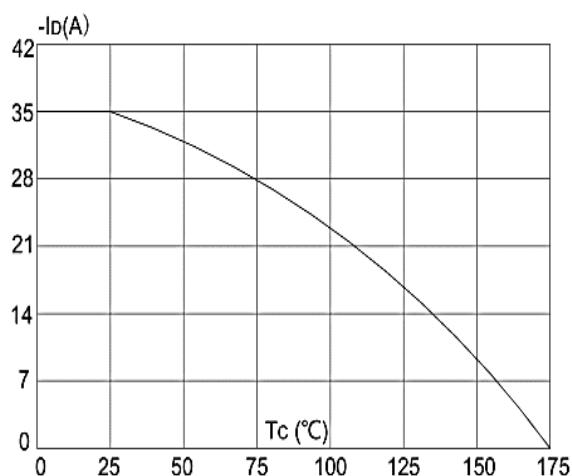


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

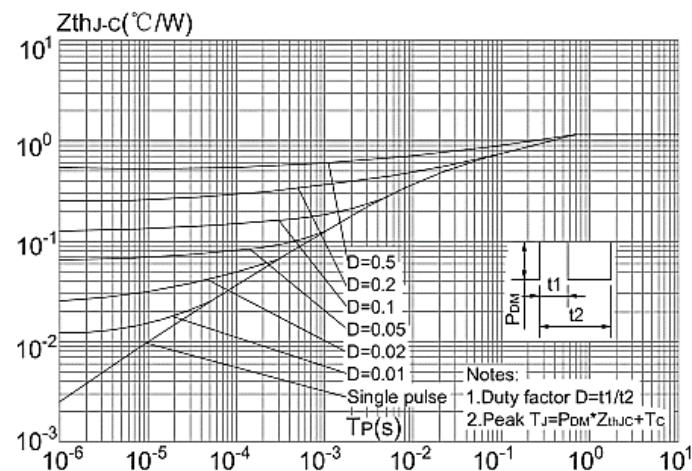
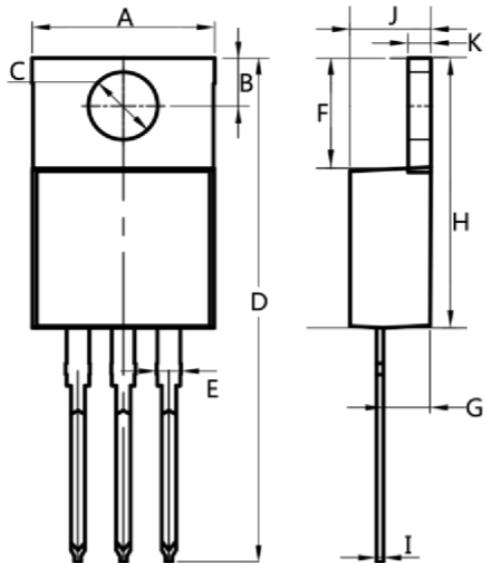


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

5. Package Mechanical Data

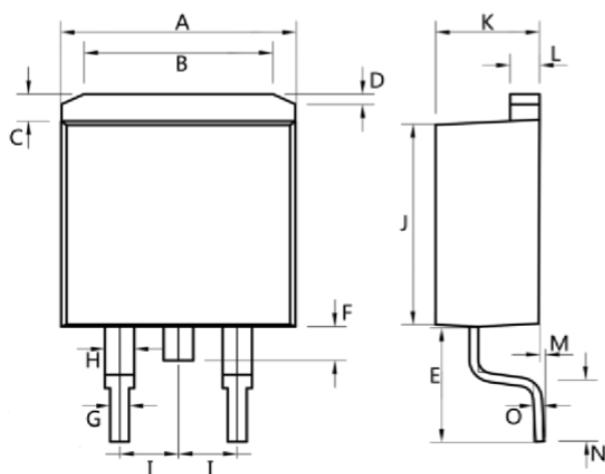
TO-220 Package



Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

TO-263 Package



Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter